

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

- 1-14. (Canceled)
15. (Currently amended) A method of mounting an electrical connector to a substrate, comprising:
- providing an electrical connector having a contact and a hold down;
 - providing a substrate having a pad;
 - securing said contact to said pad on said substrate during a reflow process;
 - placing said hold down into a hole in said substrate so as to permit said contact to center on said pad upon mounting to the substrate without contacting another pad on the substrate, wherein said hold down is adapted to retain said housing a distance from a surface of the substrate; and
 - securing said hold down to said substrate during said reflow process, wherein said hold down is manufactured to secure to said substrate subsequent to said securing of said contact, wherein said hold down is adapted to limit flattening of said contact during said reflow process, and wherein said hold down and said reflow process enable said contact to move freely to center on and become secured to the pad during said reflow process while solder used for said securing the hold down remains substantially liquid.
16. (Original) The method as recited in claim 15, wherein said securing comprises soldering said hold down to said substrate.
17. (Previously presented) The method as recited in claim 15, further comprising constructing said electrical connector such that it remains substantially parallel to the substrate when mounted thereon.
18. (Original) The method as recited in claim 15, further comprising balancing said electrical connector on said substrate such that said electrical connector remains substantially parallel to said substrate during said securing.
19. (Original) The method as recited in claim 15, wherein said electrical connector is a ball grid array connector.

DOCKET NO.: FCI-2550
Application No.: 09/691,811
Office Action Dated: August 13, 2003

PATENT

20-46. (Canceled)